# METHOD FOR PACKAGING A SEMICONDUCTOR DEVICE

## ABSTRACT OF THE INVENTION

A method for packaging a semiconductor device includes forming through holes (12) in a base substrate (10) and depositing a conductive material (14) on a first side (16) of the base substrate (10) to form a conductive layer (18) such that the conductive material (14) fills the through holes (12). The conductive layer (18) is patterned and etched to form interconnect traces and pads (22). Conductive supports (24) are formed on the pads (22) such that the conductive supports (24) extend through respective ones of the through holes (12).

[Figure 8]